



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

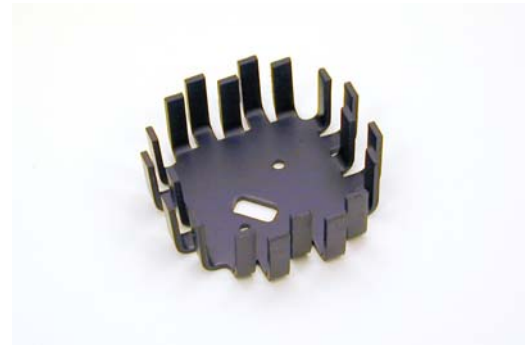
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

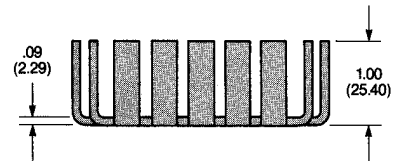
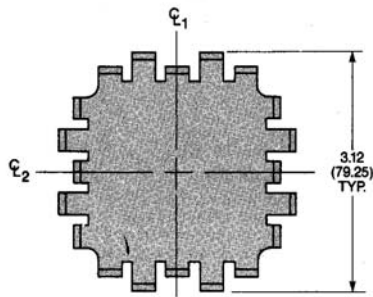
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



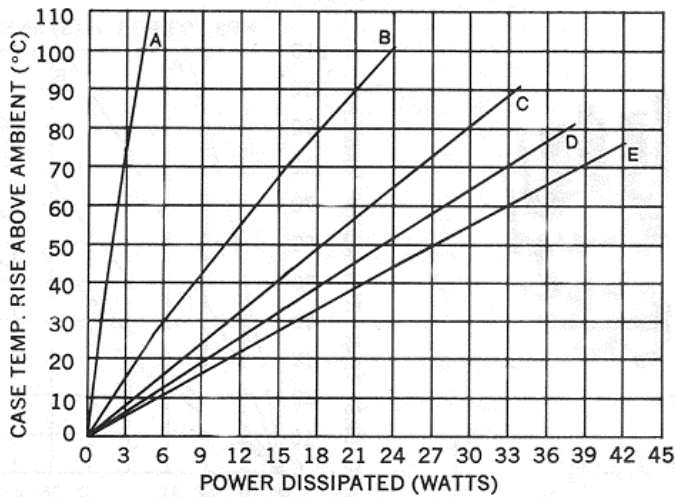
METAL CASE, CASE-MOUNTED SEMICONDUCTORS



HP3 Series for Single TO-3 or Stud Mount



HP3-T03-CB w/2N3055 (TO-3) TRANSISTOR



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

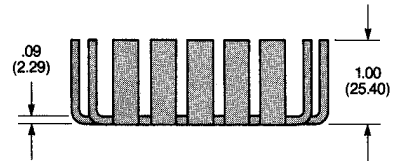
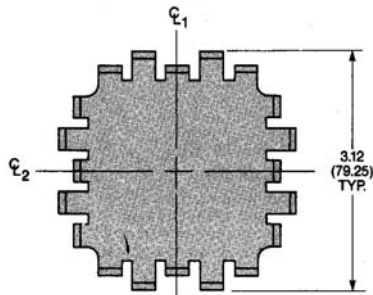
- Thermal Resistance Case to Sink is 0.1-0.3 °C/W w/Joint Compound.
- Derate 1.0 °C/watt for unplated part in natural convection only.

Ordering Information

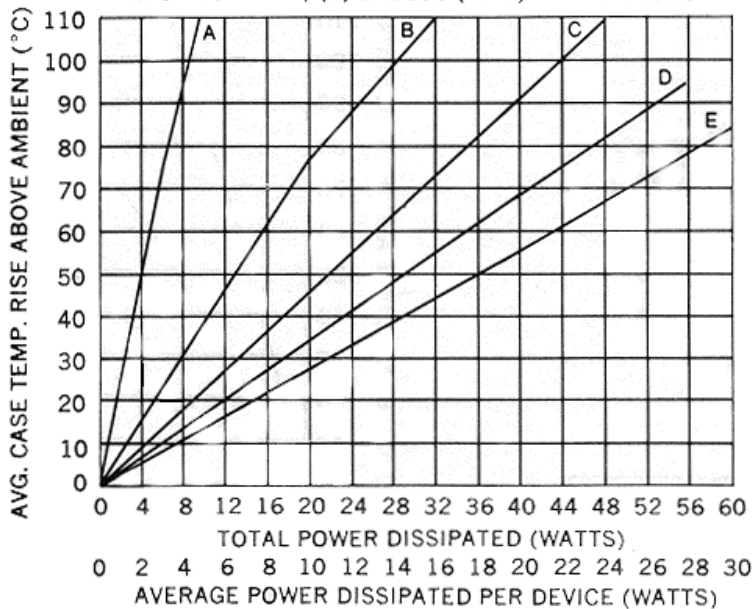
CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
HP3-000-U	HP3-000-CB	HP3-000-B	Undrilled	--	55.0
HP3-T03-U	HP3-T03-CB	HP3-T03-B	T0-3	16	55.0
HP3-T03-33U	HP3-T03-33CB	HP3-T03-33B	T0-3 IC	17	55.0

HP3-T03-44U	HP3-T03-44CB	HP3-T03-44B	T0-3 PANEL MOUNT	31	55.0
HP3-436-U	HP3-436-CB	HP3-436-B	T0-3 (4 PIN)	18	55.0
HP3-T015-U	HP3-T015-CB	HP3-T015-B	T0-15, D0-5	23	55.0
HP3-T06-U	HP3-T06-CB	HP3-T06-B	T0-6, T0-36	19	55.0
HP3-420-U	HP3-420-CB	HP3-420-B	UNIVERSAL	27	55.0

HP3 for Dual TO-3 Outline



HP3-T03-4CB w/(2) 2N3055 (TO-3) TRANSISTORS



DESCRIPTION OF CURVES

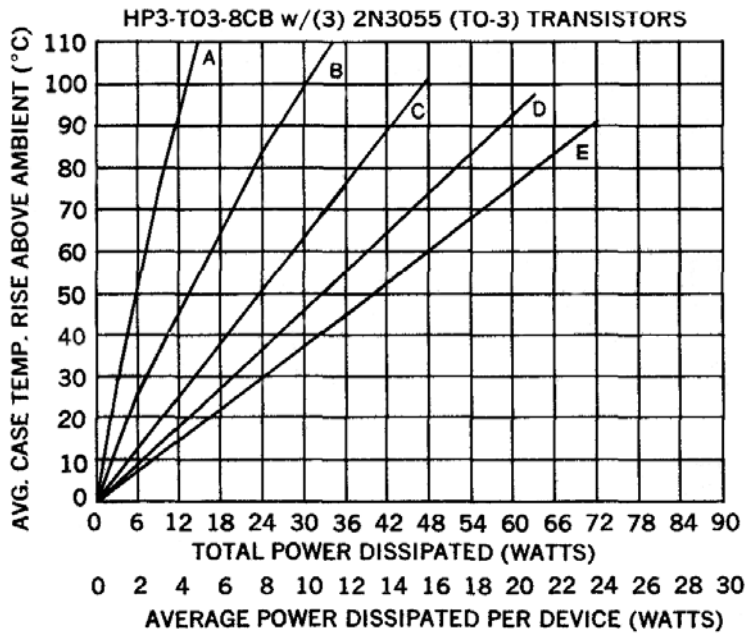
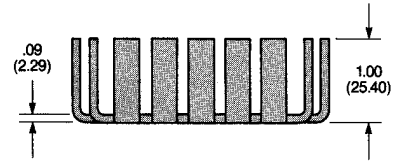
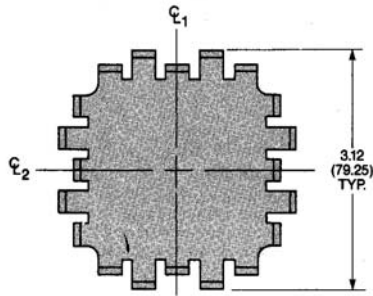
- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.1-0.3 °C/W w/Joint Compound.
- Derate 2.0 °C/watt for unplated part in natural convection only.

Ordering Information

CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
HP3-T03-4U	HP3-T03-4CB	HP3-T03-4B	Two TO-3s	6	55.0
HP3-437-U	HP3-437-CB	HP3-437-B	Two TO-3s (4 pin)	12	55.0

HP3 for Three TO-3 Outline



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

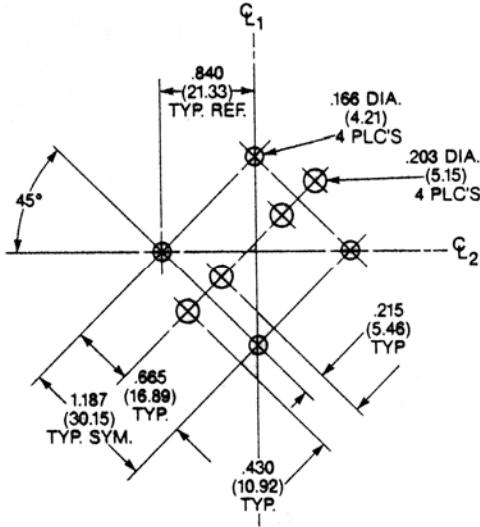
- Thermal Resistance Case to Sink is 0.1-0.3 °C/W w/Joint Compound.
- Derate 3.0 °C/watt for unplated part in natural convection only.

Ordering Information

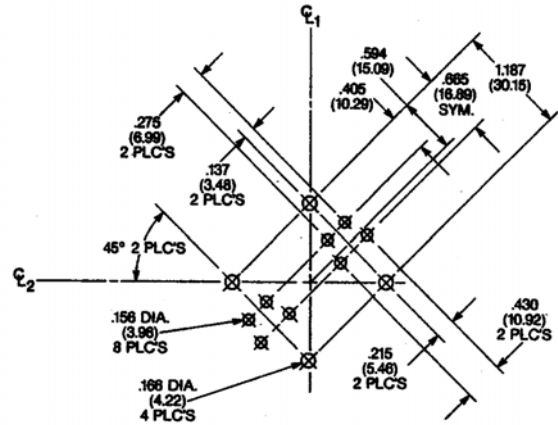
CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
HP3-T03-8U	HP3-T03-8CB	HP3-T03-8B	Three TO-3s	13	55.0

HOLE PATTERNS

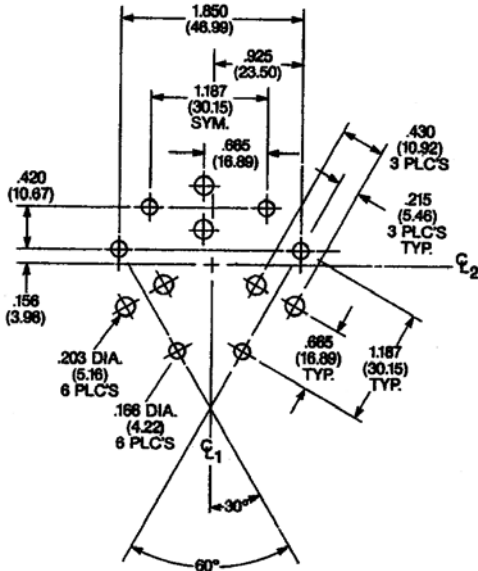
6. Hole pattern no. 124 accomodates two TO-3s. Available in HP3 series heat dissipators only.



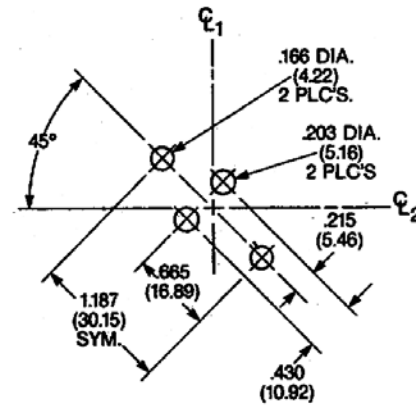
12. Hole pattern no. 437 accomodates two TO-3s (4-pin). Available in HP3 series heat dissipators only.



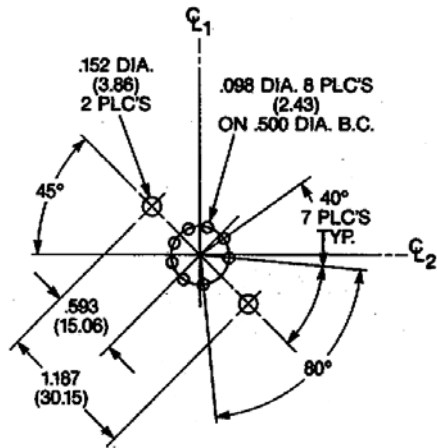
13. Hole pattern no. 186 accomodates three TO-3s. Available in HP3 series heat dissipators only.



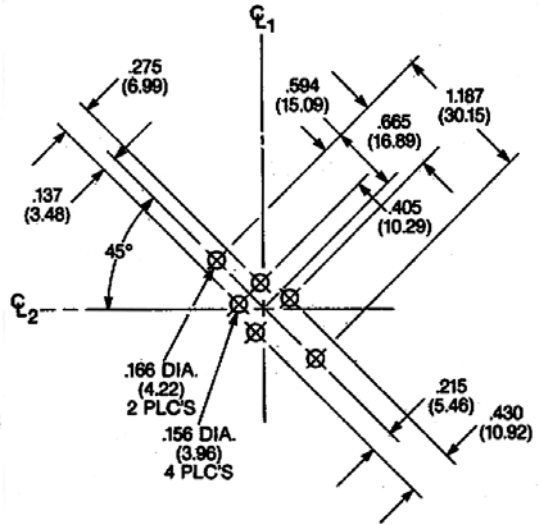
16. Hole pattern no. 1 accomodates T0-3s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



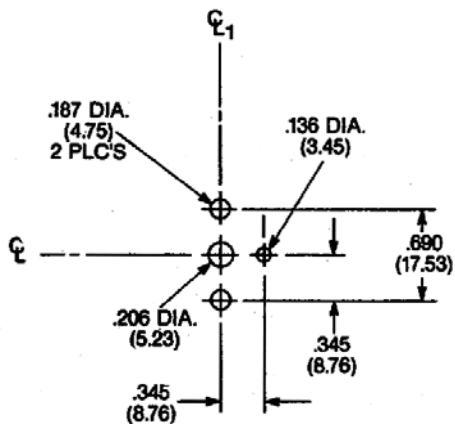
17. Hole pattern no. 202 accommodates T0-3 ICs. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



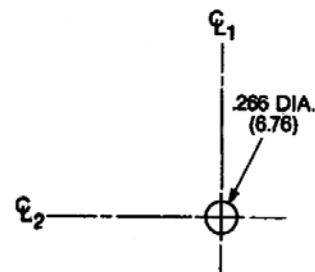
18. Hole pattern no. 436 accommodates T0-3s (4-pin). Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



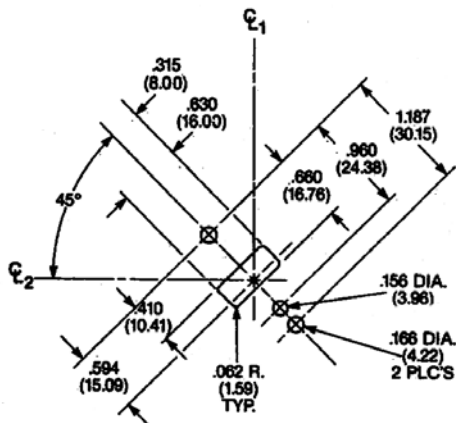
19. Hole pattern no. 2 accommodates T0-6s or T0-36s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



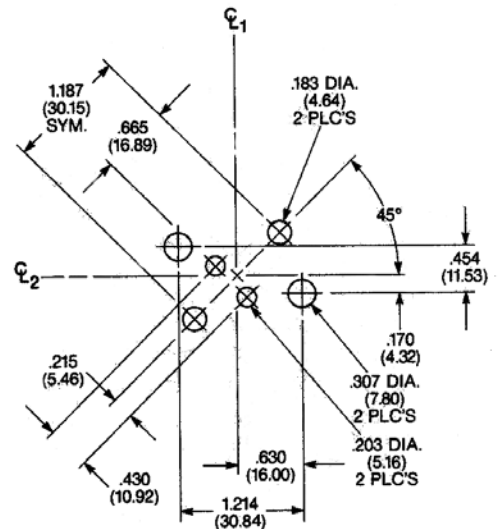
23. Hole pattern no. 3 accommodates T0-15s, D0-5s and other 1/4" stud mount devices. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



27. Hole pattern no. 420 (Universal) accommodates T0-3s, T0-66s, T0-126s, T0-127s, or T0-220s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



31. Hole pattern no. 213 accommodates one TO-3 (panel mounted). Available in HP1 and HP3 series heat dissipators only.



CTS IERC, Heat Sinks and Thermal Management Solutions

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